



# HIGH-FREQUENCY LAYOUT

Best Practices for PCBA Design

GERRY CALLAHAN

# Agenda

- **Why every design needs to consider High Frequency Layout**
- **Why EMI and SI matter**
  - Electro-Magnetic Interference
  - Signal Integrity
- **Circuit Theory and Wave Theory**
- **The difference between Ground and Return**
- **When is a signal “High Frequency”**
- **Recommendations**
  - Good Practices
  - PCB Stackups
- **Questions and discussion**

# Considering High Frequency Layout

- There may be parts of a design that include high frequencies in non-obvious ways
- If a layout could radiate, it's also susceptible to interference
- Requirements change, parts change

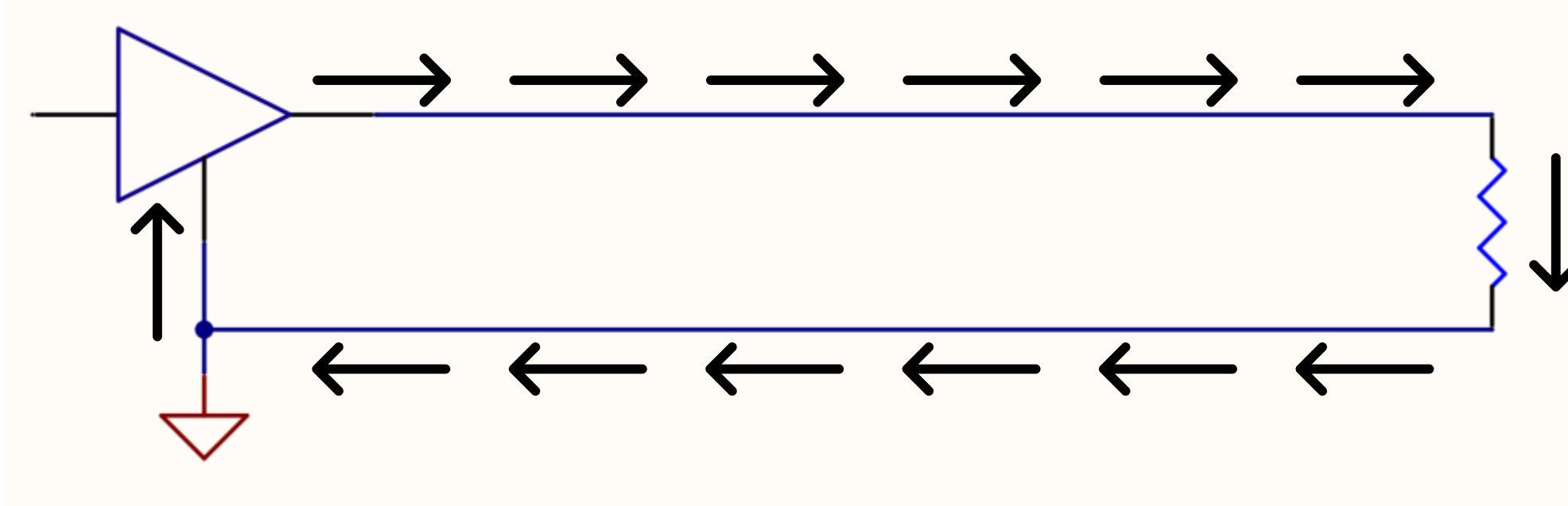
# EMI and SI

- Everything we sell must obey FCC rules
- Even if a circuit doesn't have high-frequency sources, it could pick up signals that cause problems
- One part of a circuit could interfere with other parts
- The principles for avoiding EMI problems are very similar to maintaining good SI

**Good layout habits will pay off later**

# CIRCUIT THEORY AND WAVE THEORY

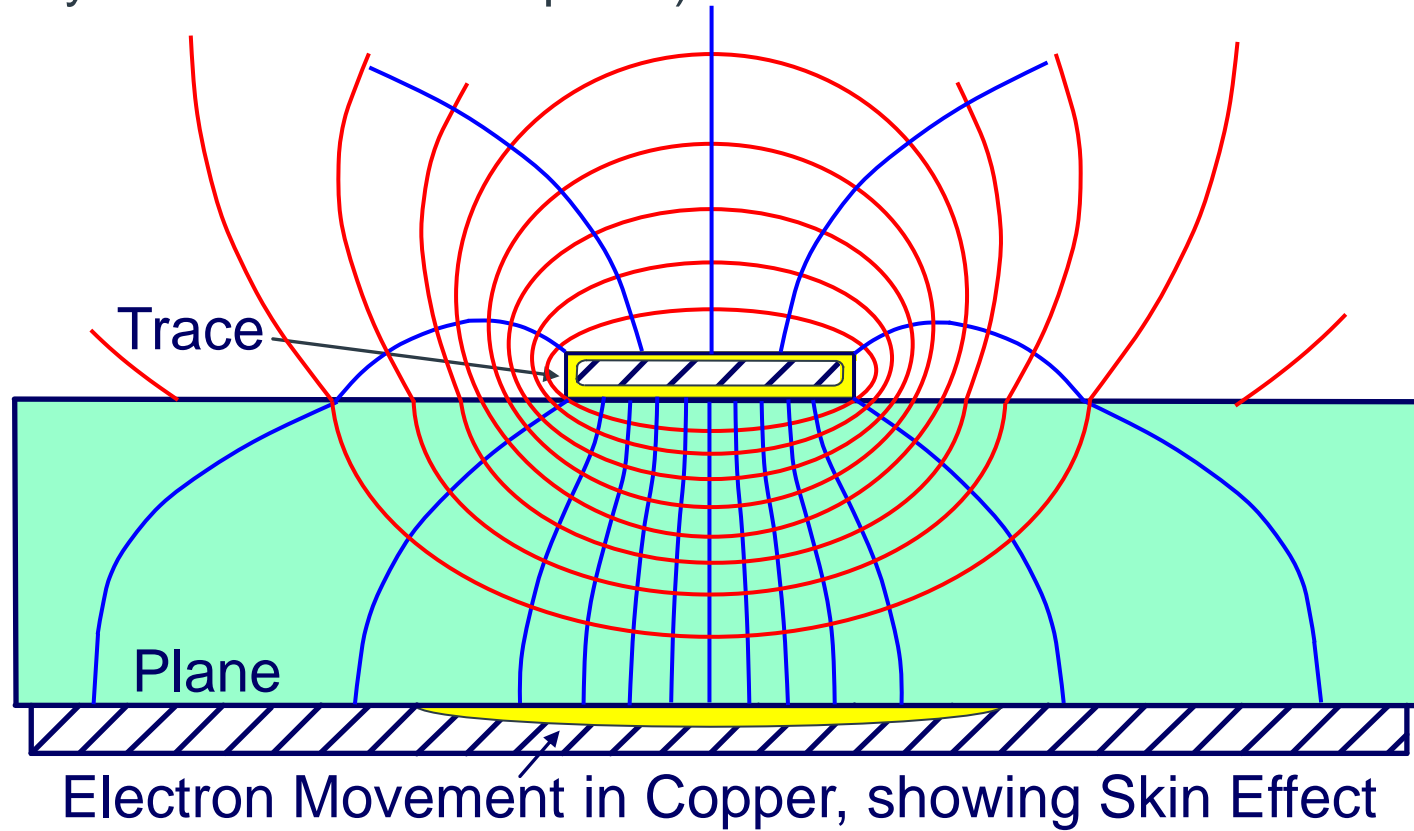
# Circuit Theory...



... is WRONG

# Voltage and Magnetic Fields

Microstrip (Outer layer trace and return plane)



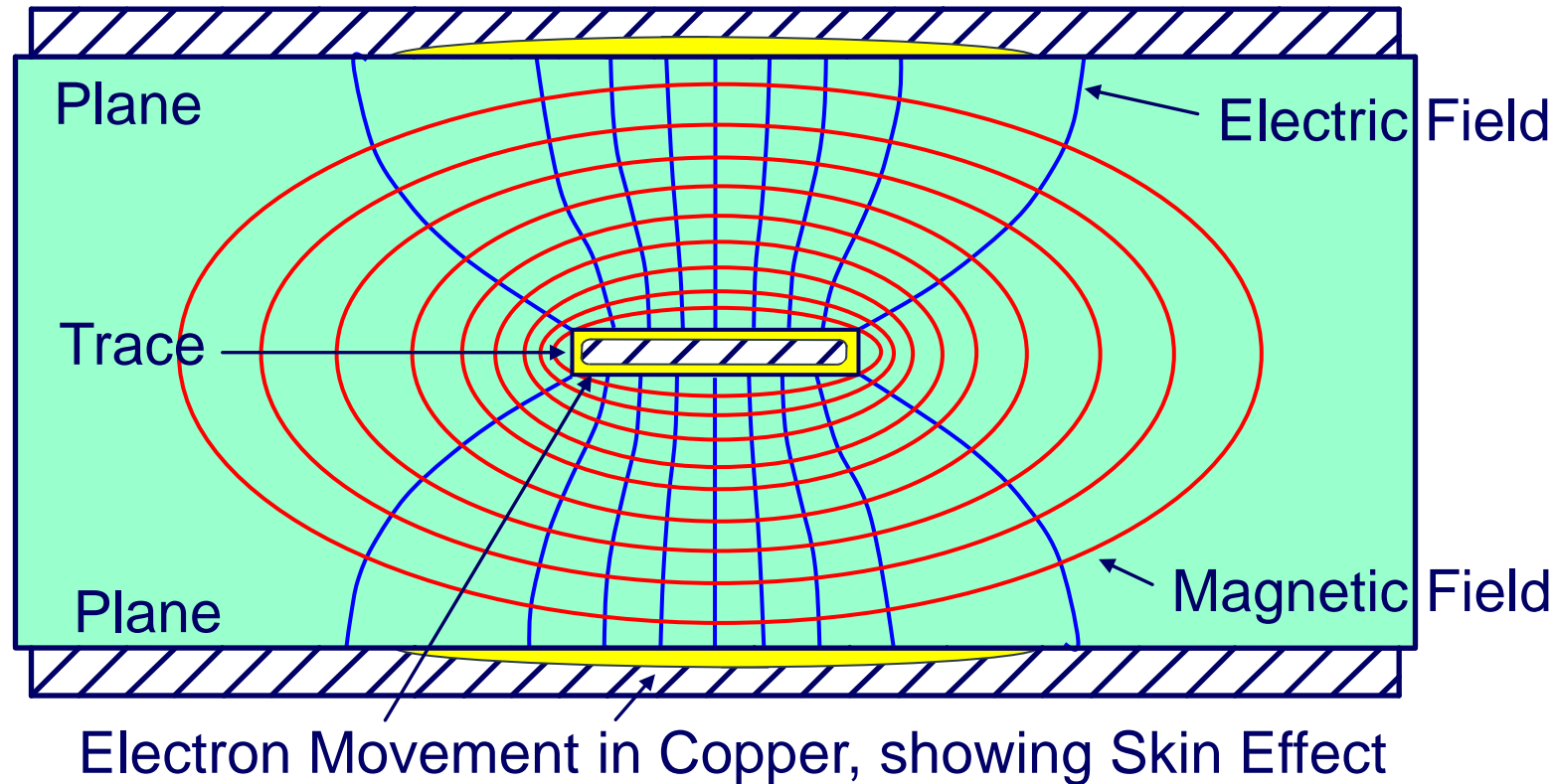
Original source:

**RHARTLEY**  
ENTERPRISES  
CONTROL OF NOISE, EMI & SI

Moderate Volume Fields (EM Wave), Mostly Contained.

# Voltage and Magnetic Fields

Stripline (Inner layer trace and return planes)



Original source:

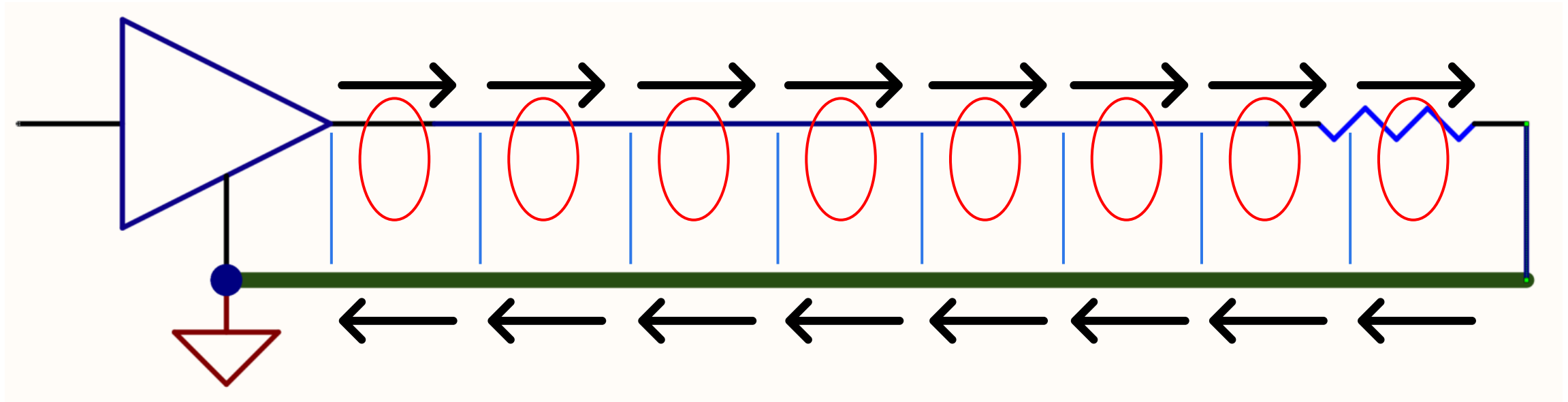
**RHARTLEY**  
ENTERPRISES  
CONTROL OF NOISE, EMI & SI

Low Volume Fields (EM Wave), Completely Contained.



# Voltage, Current, and Waves

- How does the signal go from the source to the load?



Energy is in the Waves (traveling *between* the layers)

# Path of Return Current

- 2-Layer board, components and signals on top, “ground” plane on bottom



# Path of Return Current

- Same layout, except there's a cutout in the ground plane (between source and load)



# Path of Return Current

- Same layout, except there's a cutout in the ground plane (under the trace)



E-M Fields around the ground break are a *mess!*

# GROUND AND RETURN

# Ground v. Return

- The only true Ground is “Earth Ground”
- Chassis is often called “Ground”
  - May or may not be connected to Earth Ground
- Power Supply negative output (return) is often called “Ground”
  - But it’s usually isolated, definitely not Earth Ground
- Component data sheets often call one of the pins “Ground”
  - But it’s just the power supply return
- The shield of a coax cable is almost never “Ground”
- PCBs usually have a plane for both power and signal return, called the “Ground Plane”

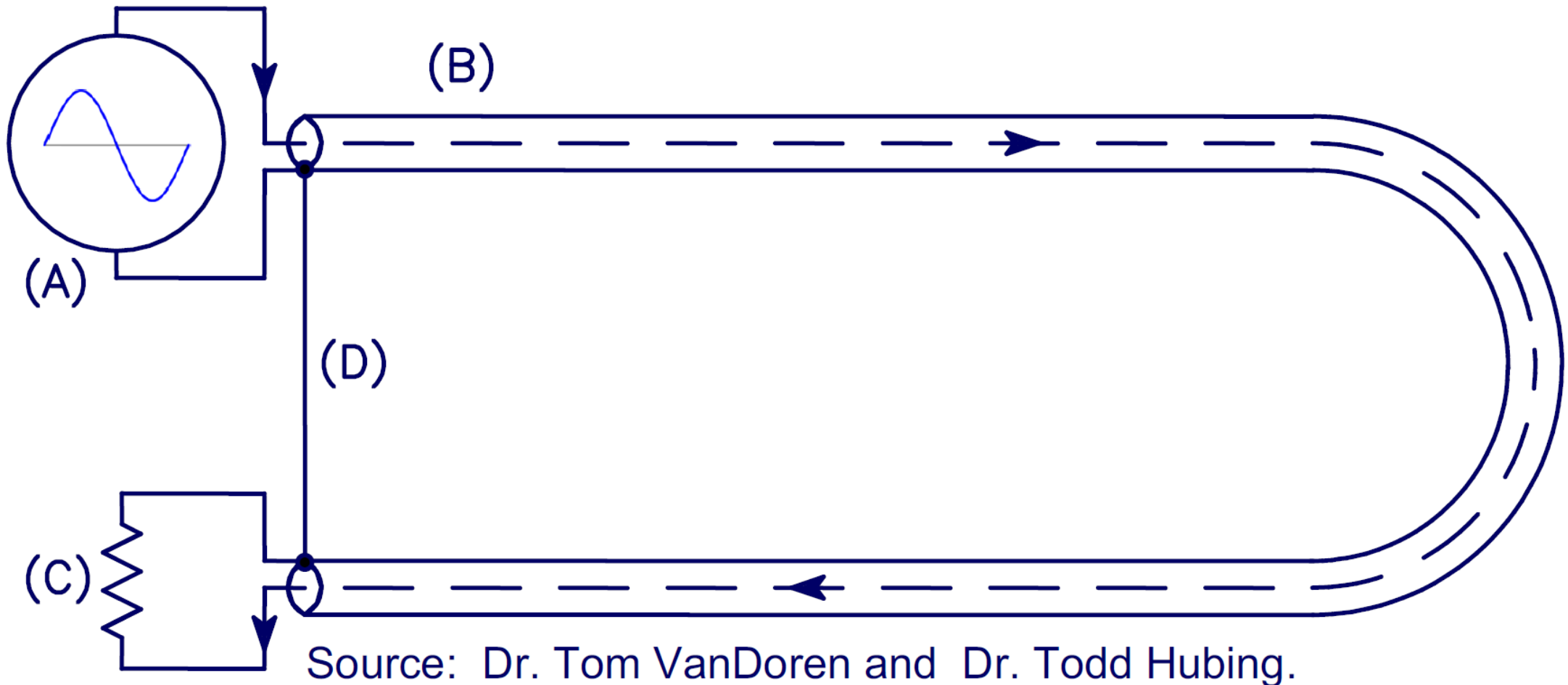
# HIGH FREQUENCY

# What makes “High Frequency”?

- Frequency ranges where it becomes a problem
- Edge rate v. Repetition rate



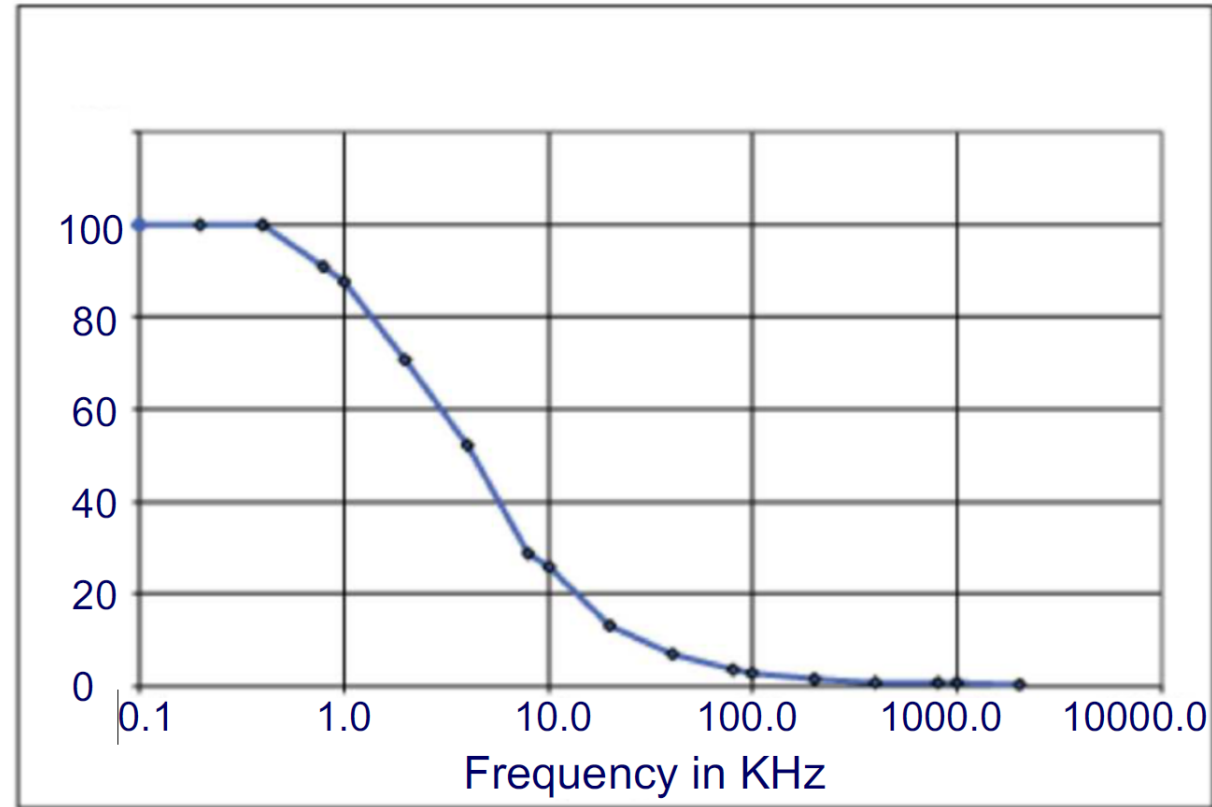
# Experiment to show that...



...Current takes the path of Least Impedance

# Experiment to show that...

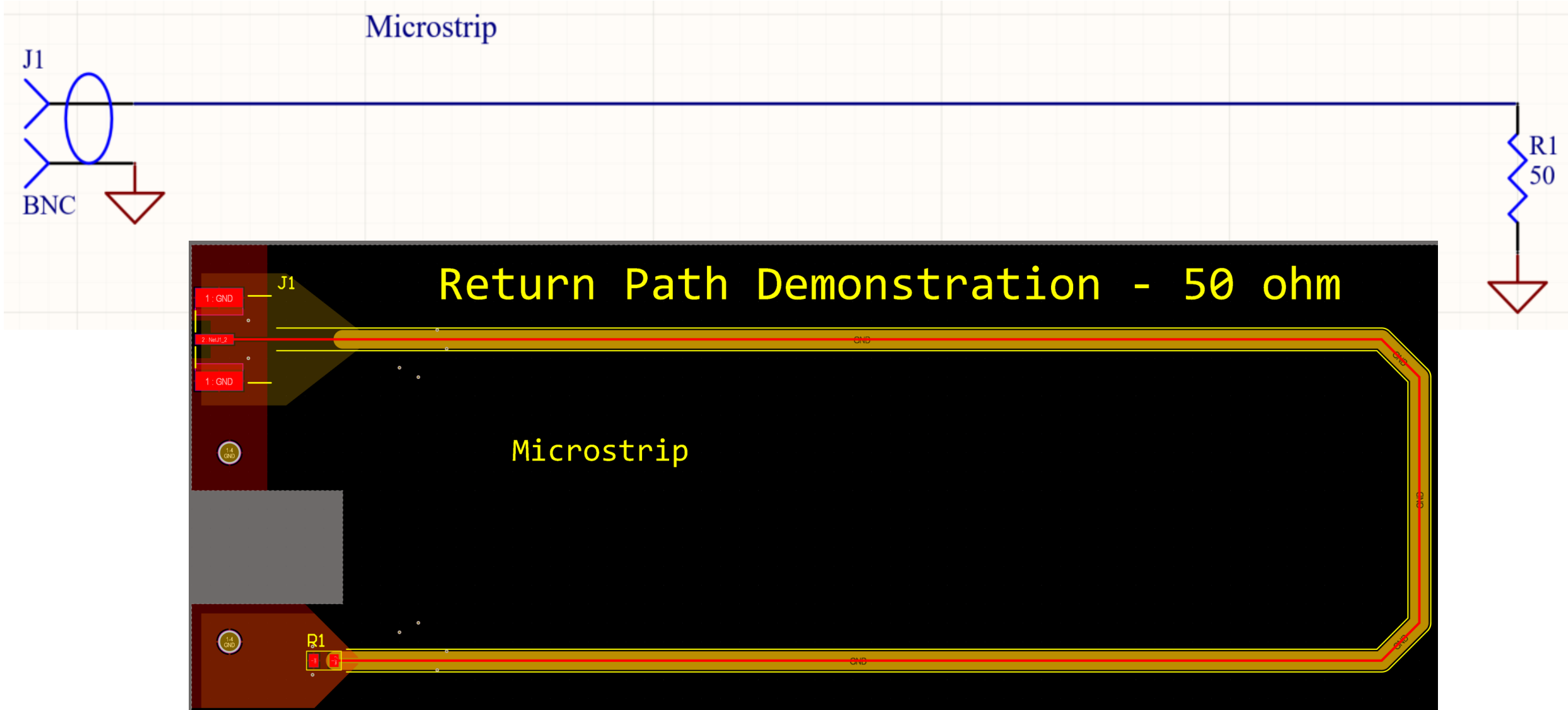
% of Total Current Flowing in the Strap



Source: Dr. Todd Hubing.

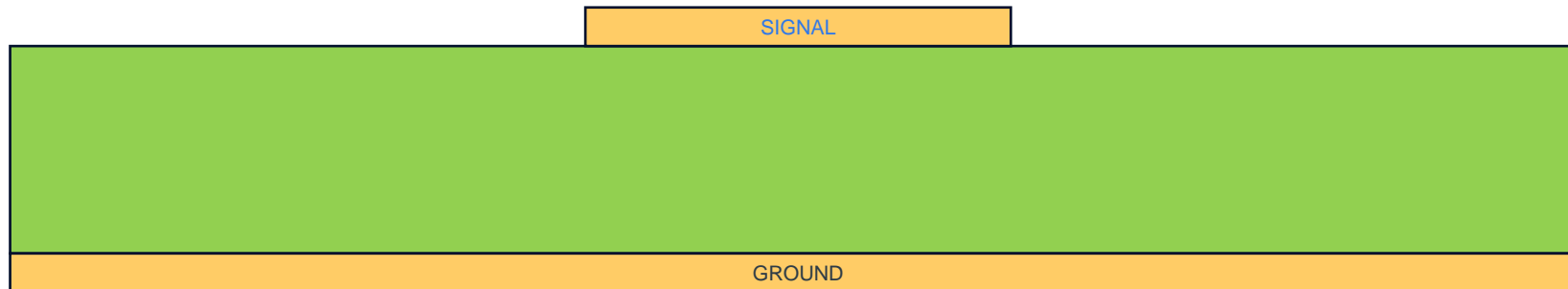
...Current takes the path of Least Impedance

# Same Experiment in PCBA

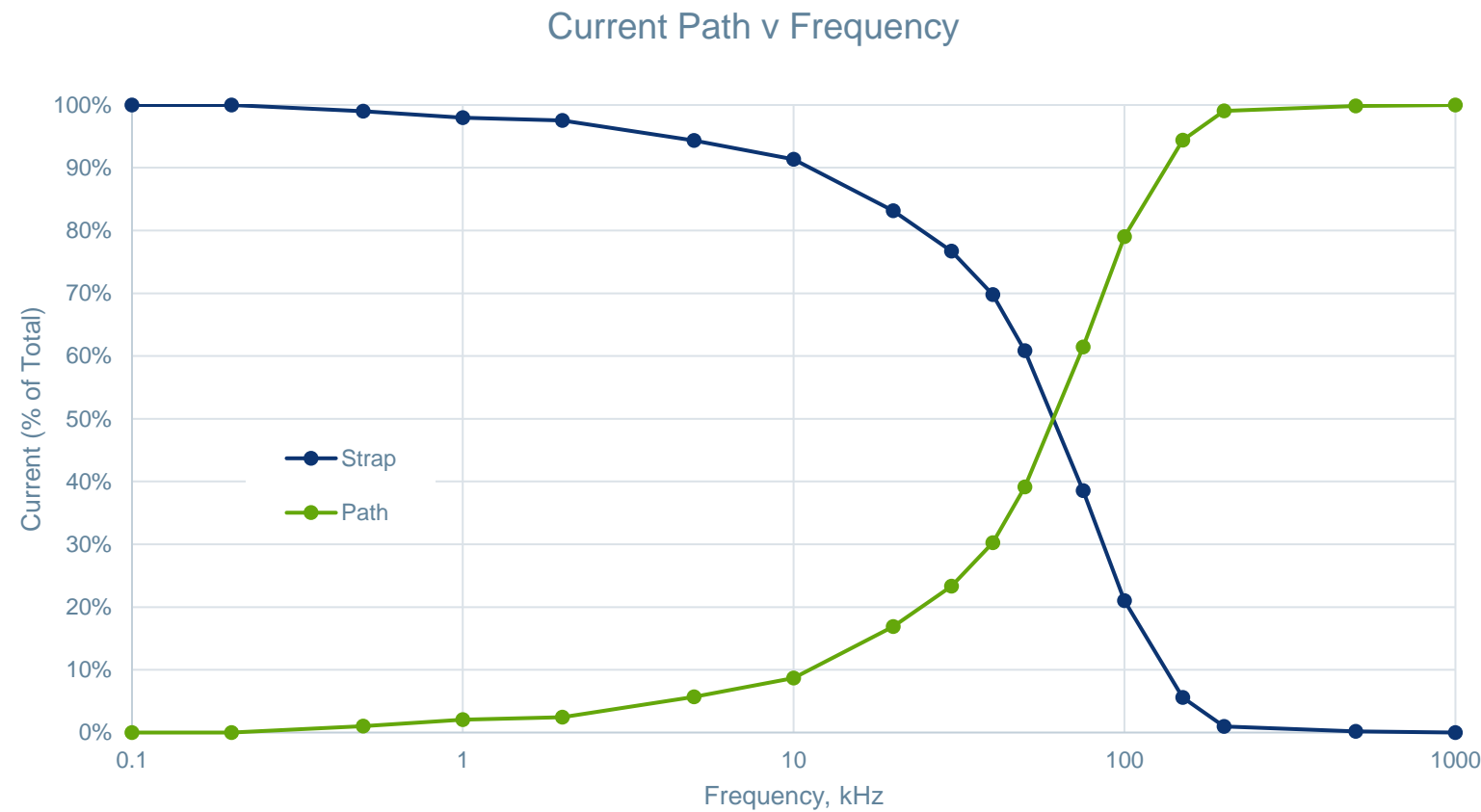


# Microstrip Transmission Line

Trace on outer layer, referenced to adjacent layer



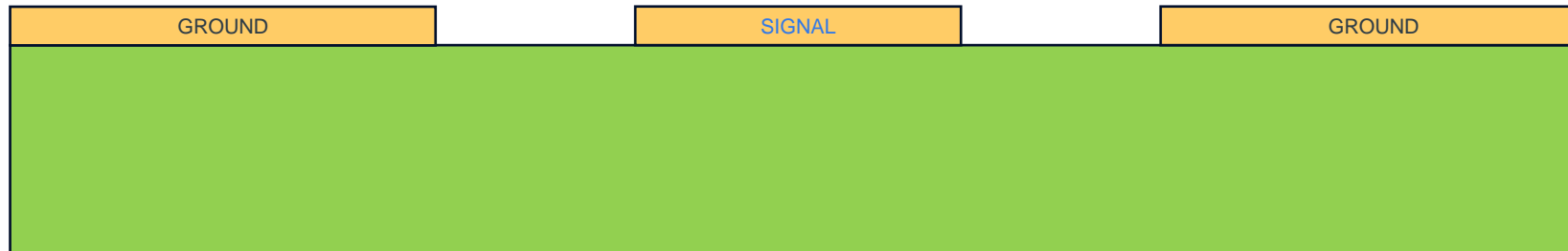
# Microstrip Results



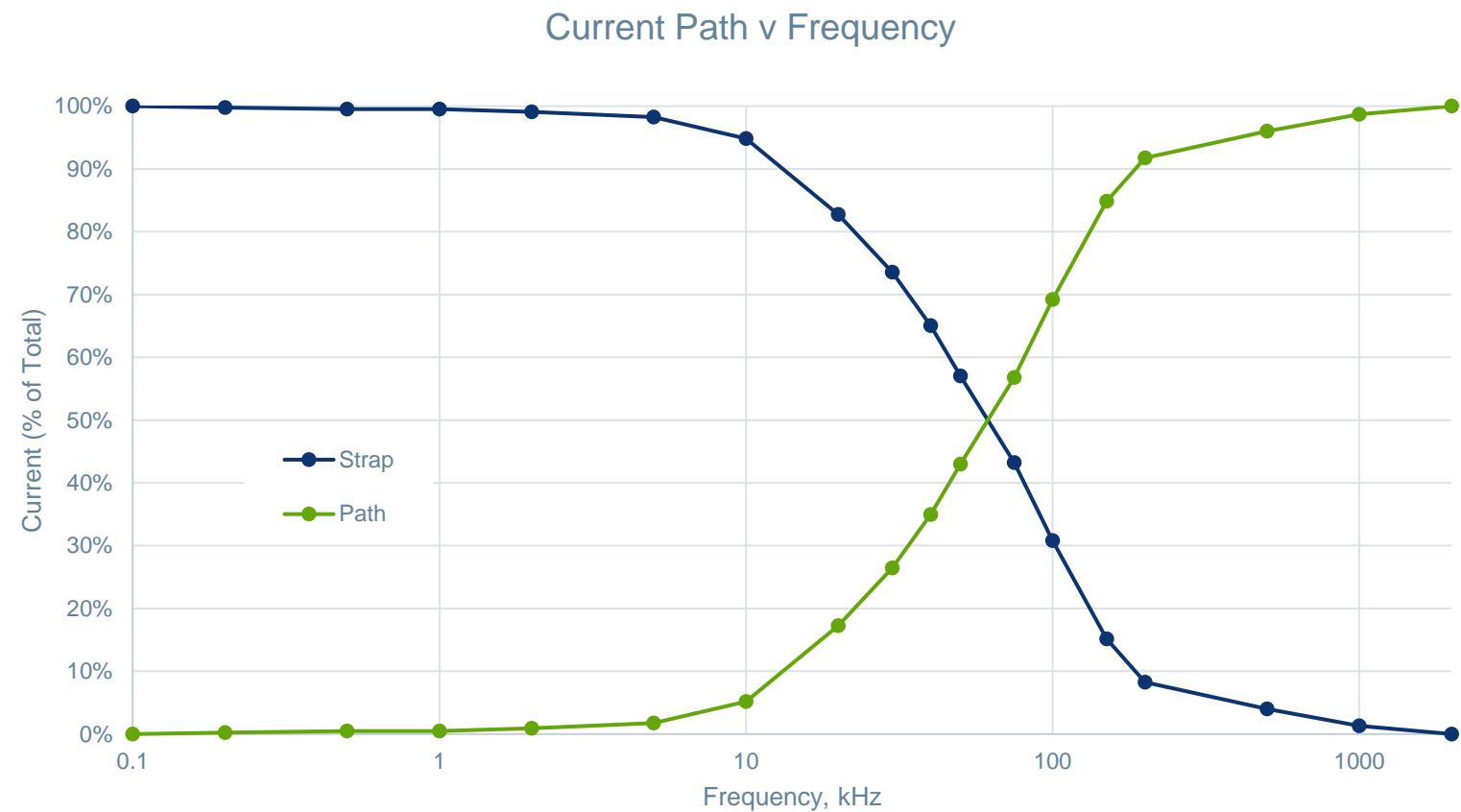
Transition complete at 200 kHz

# Coplanar Transmission Line

Trace on any layer, referenced to two traces on same layer



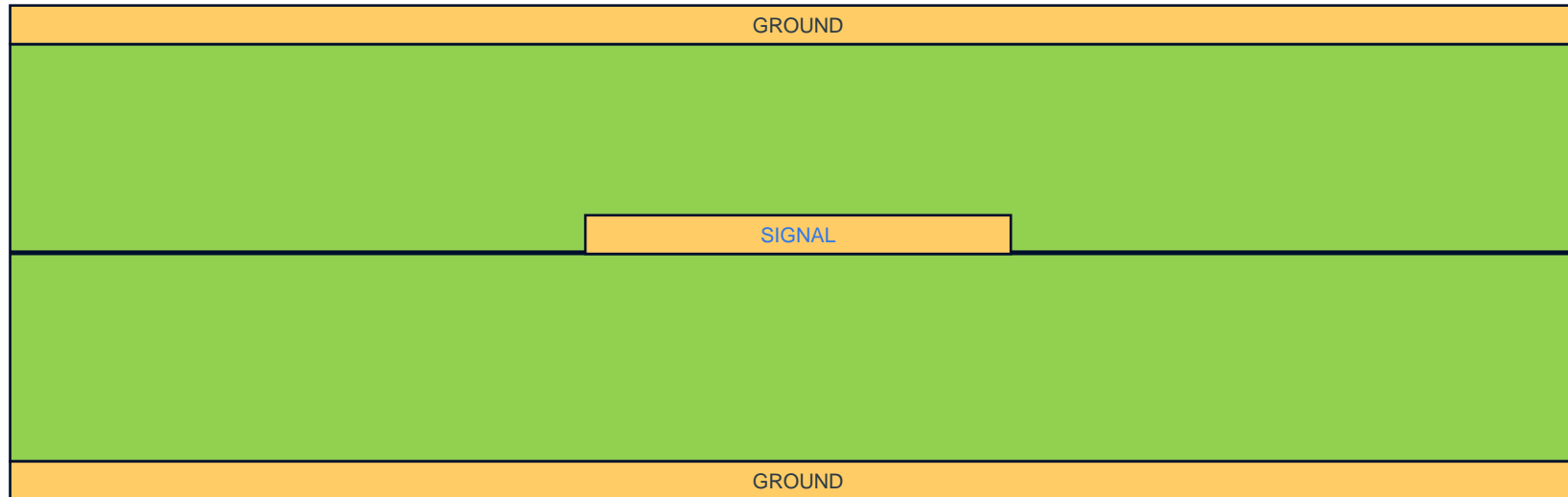
# Coplanar Results



Transition complete at 2 MHz

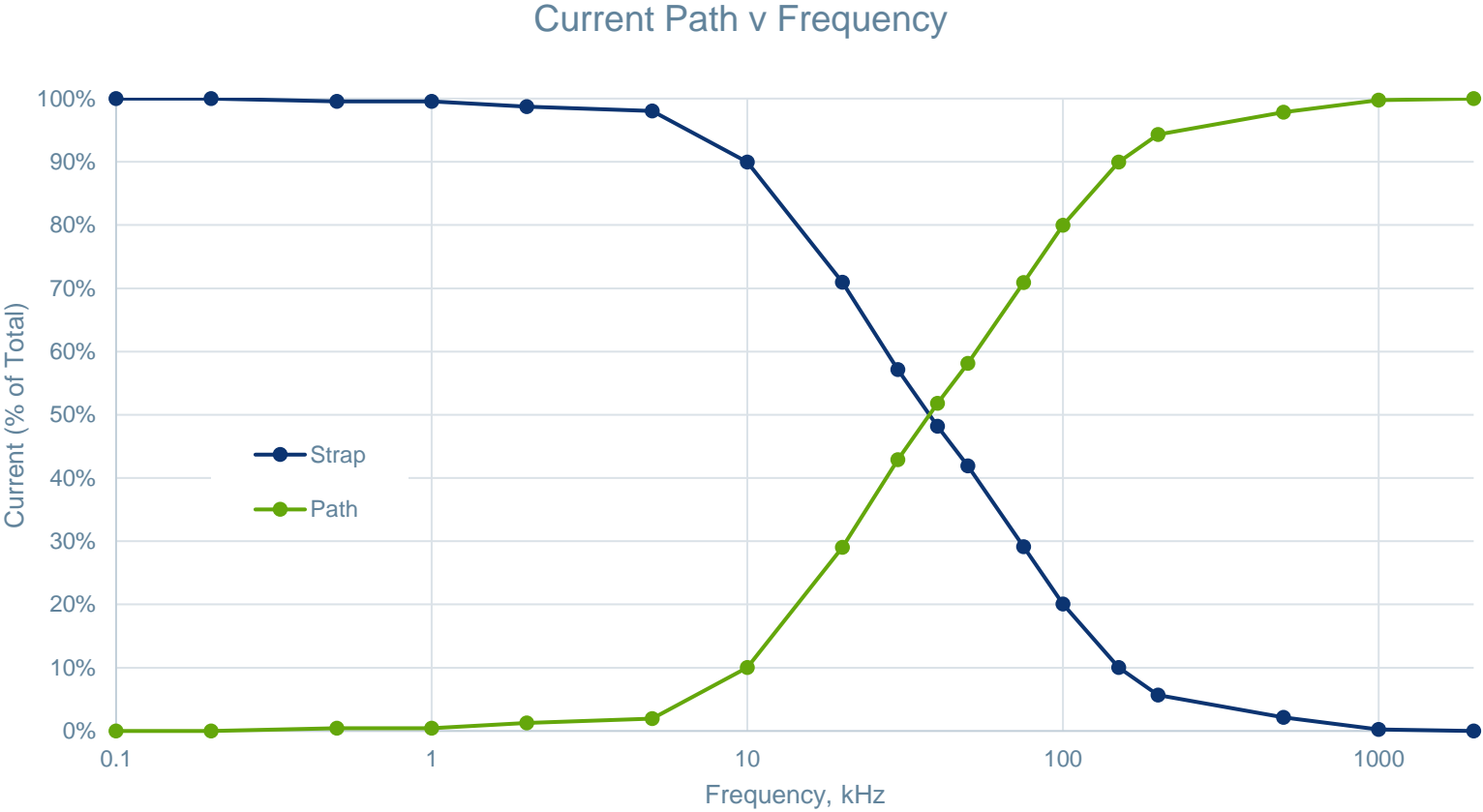
# Stripline Transmission Line

Trace on inner layer, referenced to both adjacent layers





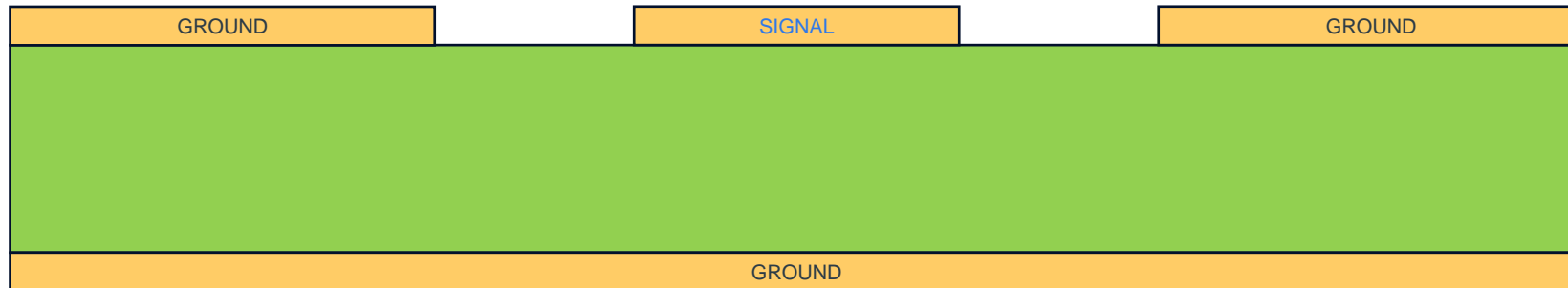
# Stripline Results



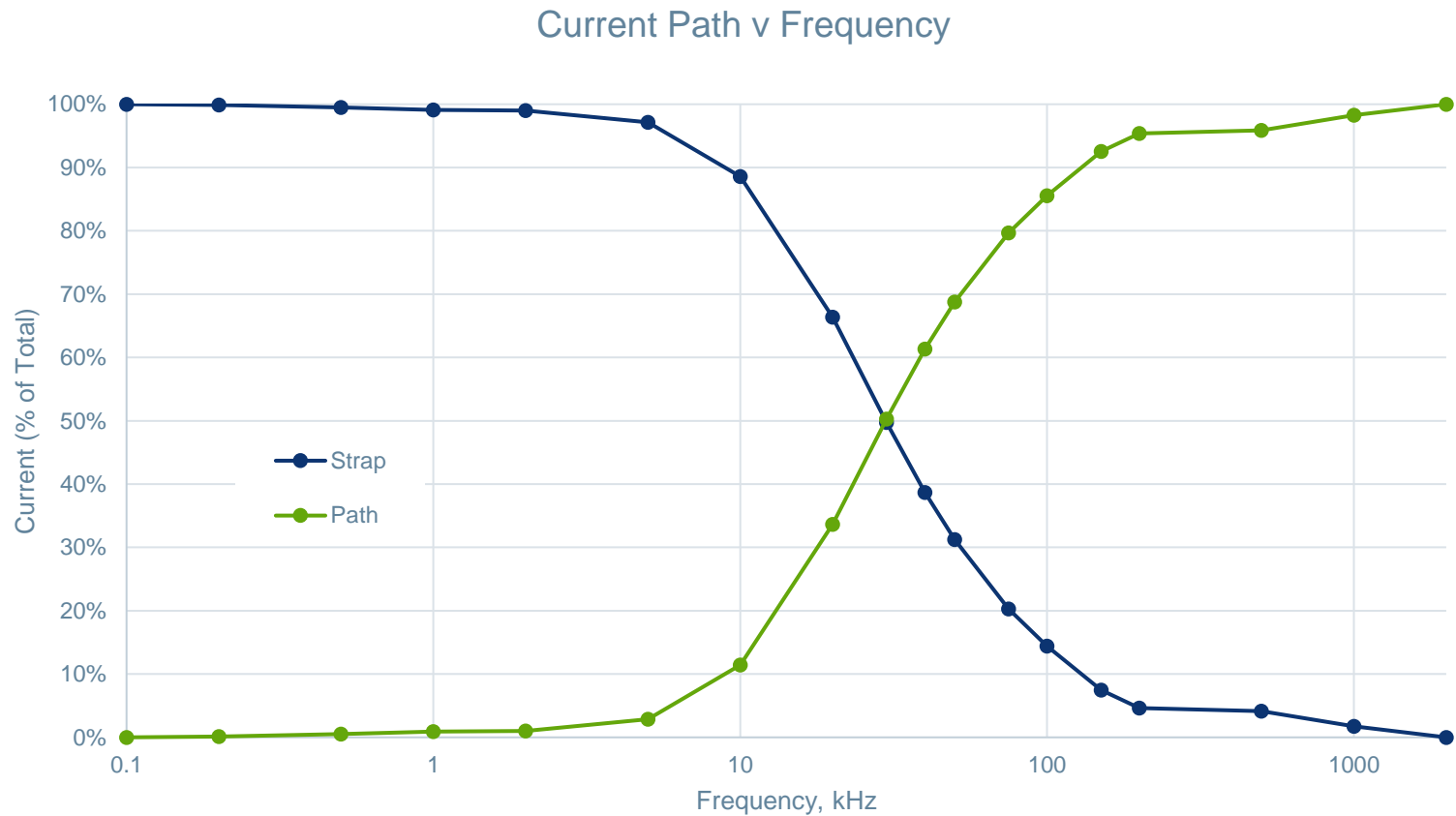
Transition complete at 1 MHz

# Coplanar with Ground Transmission Line

Trace on any layer, referenced to two traces on same layer, and adjacent layer



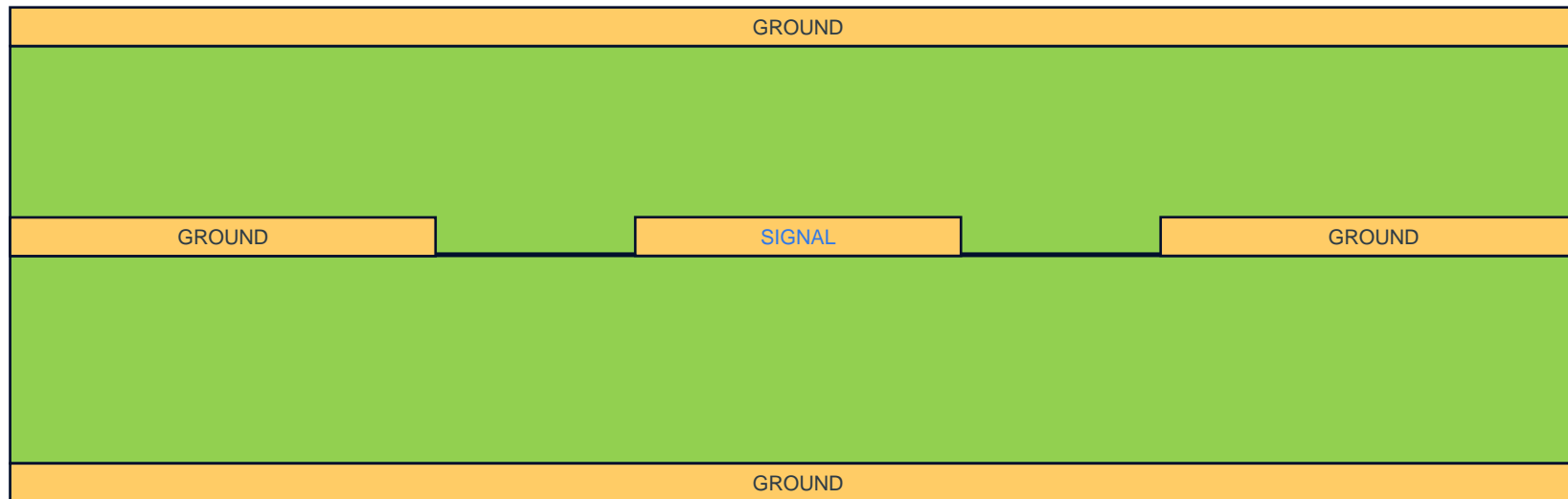
# Coplanar with Ground Results



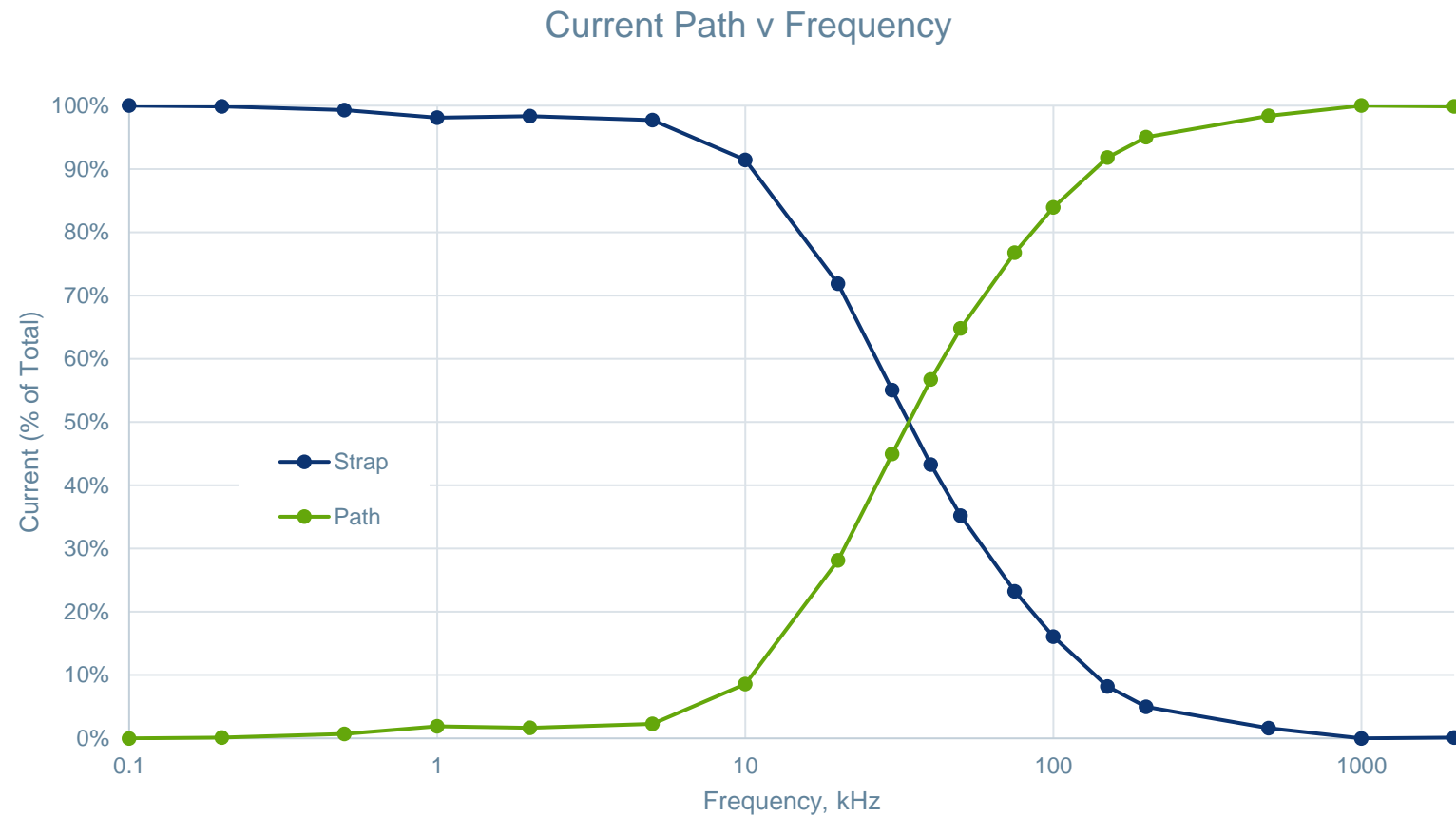
Transition complete at 2 MHz

# Coplanar with Double Ground Transmission Line

Trace on any layer, referenced to two traces on same layer, and both adjacent layers



# Coplanar with Double Ground Results



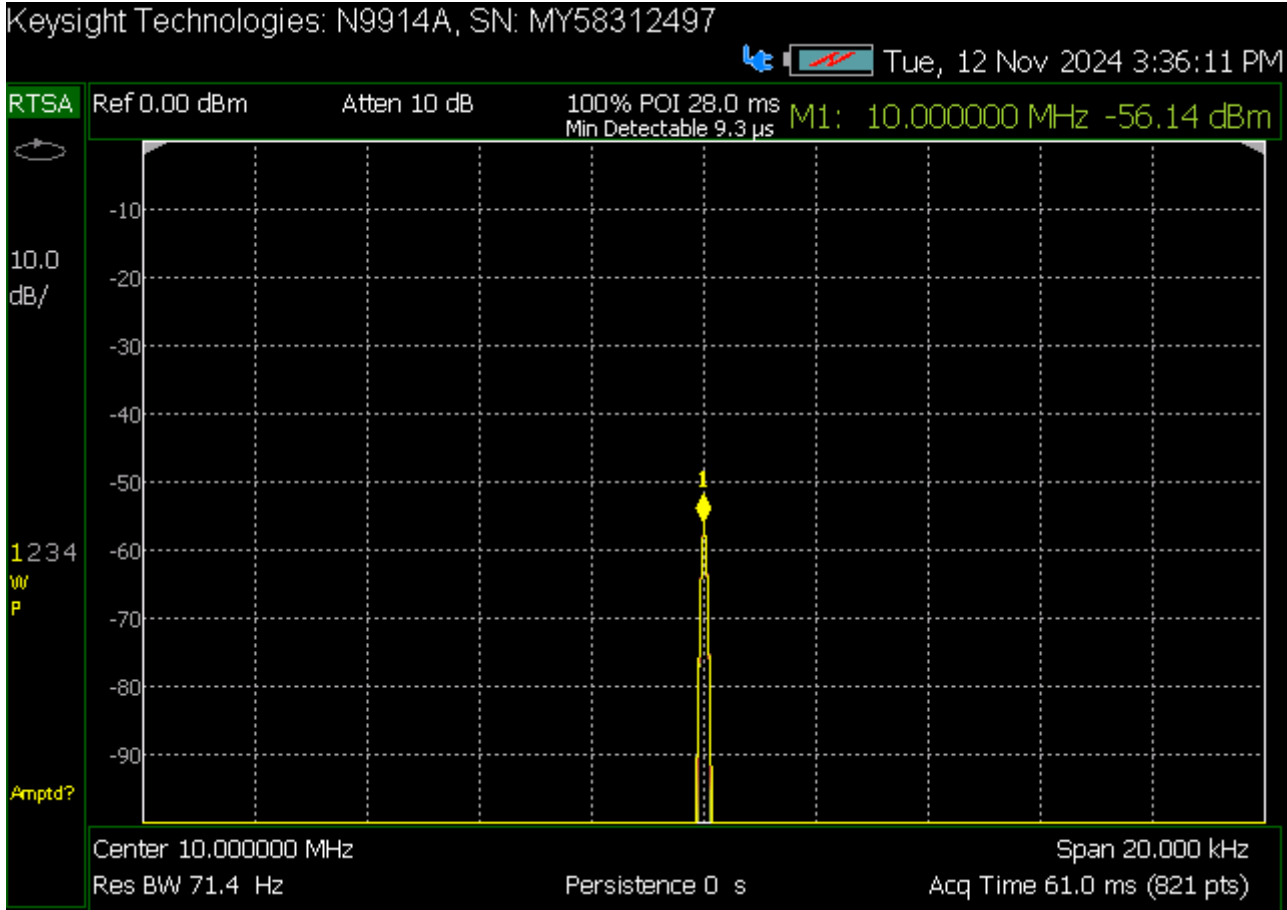
Transition complete at 1 MHz

# Comparison of Transmission Lines

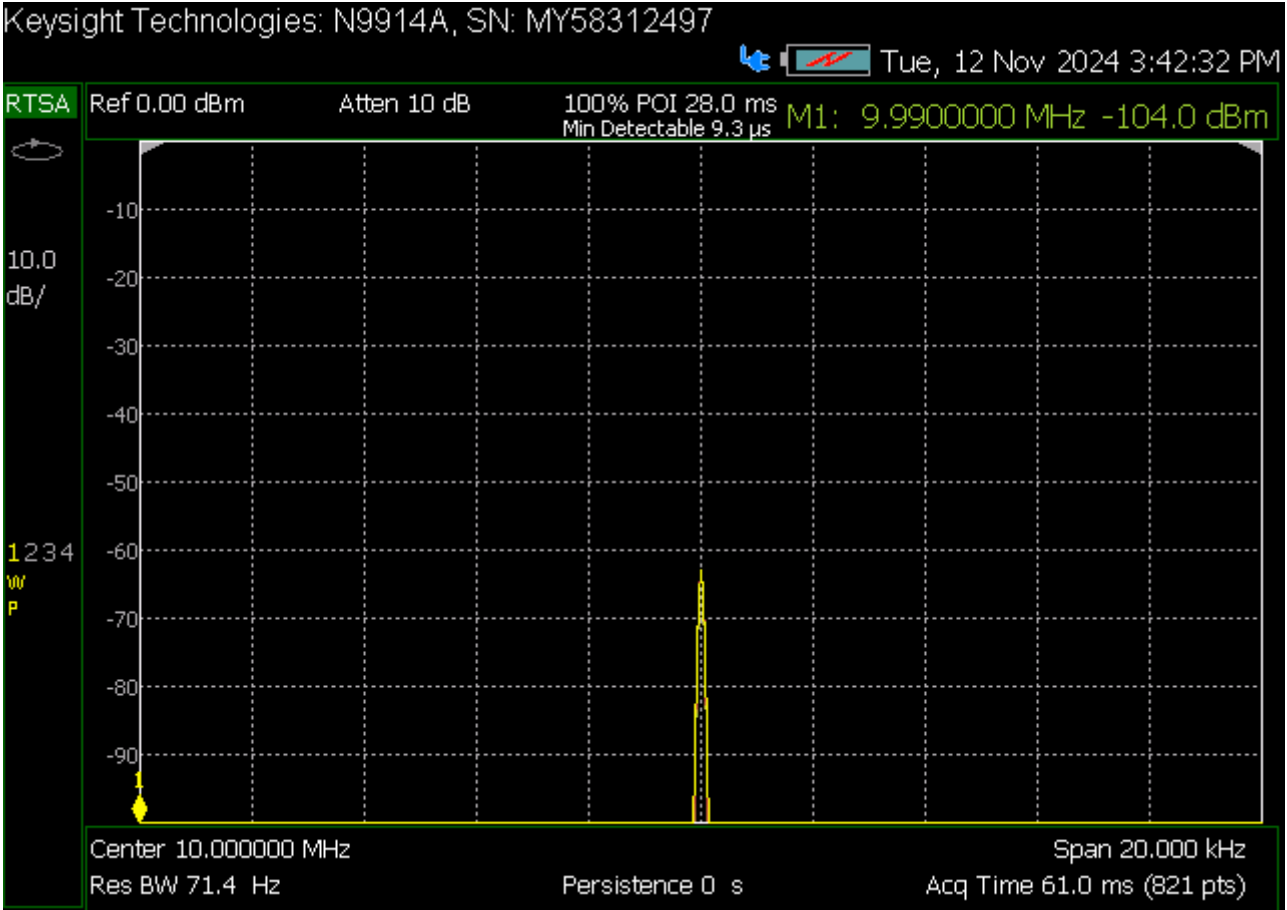
Type	Transition Frequency (kHz)
Microstrip	55.4
Coplanar	64.5
Stripline	39.7
Coplanar with Ground	31.1
Coplanar with Double Ground	34.7

Ground on Adjacent Planes = Most Effective

# Microstrip - Radiated Emission

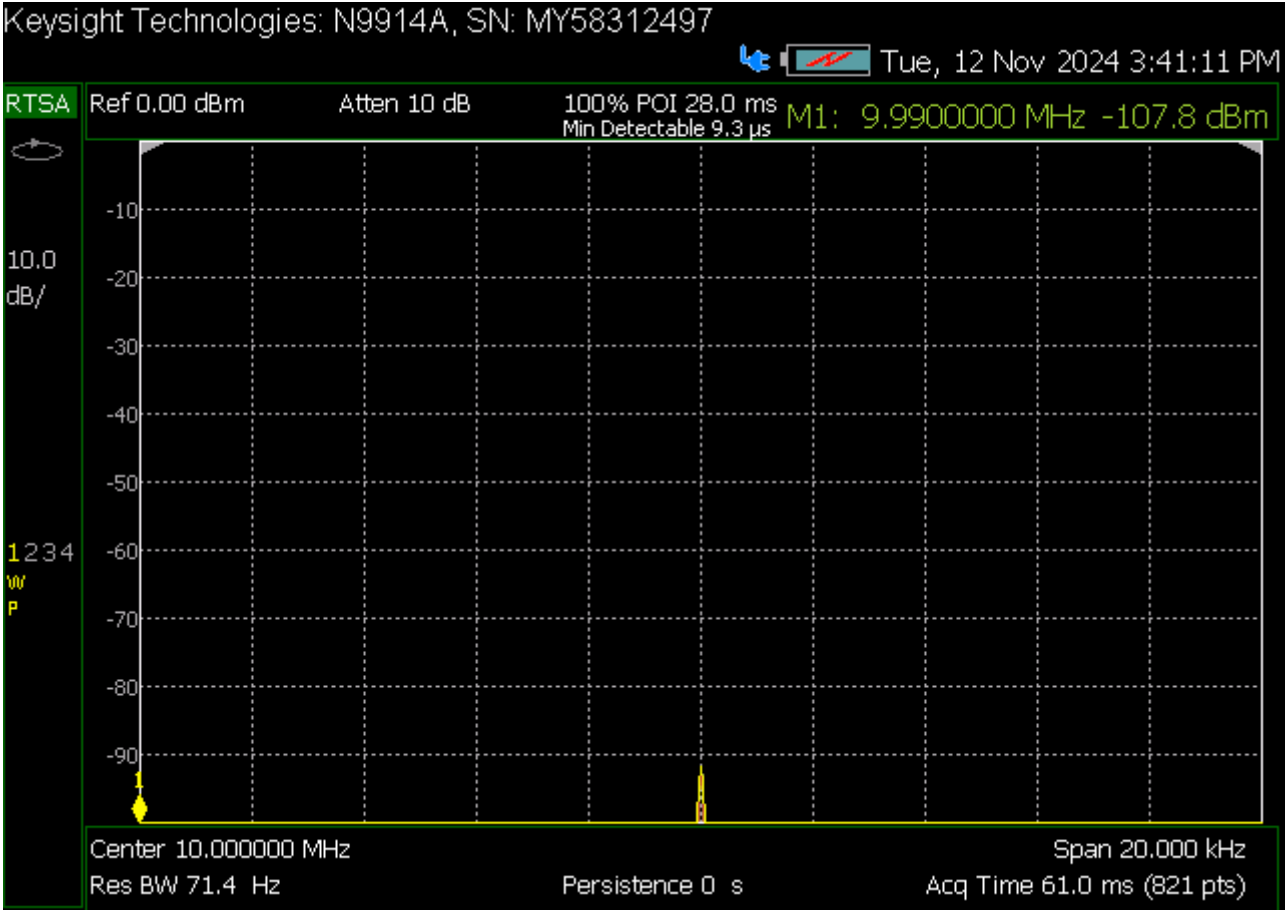


# Coplanar - Radiated Emission

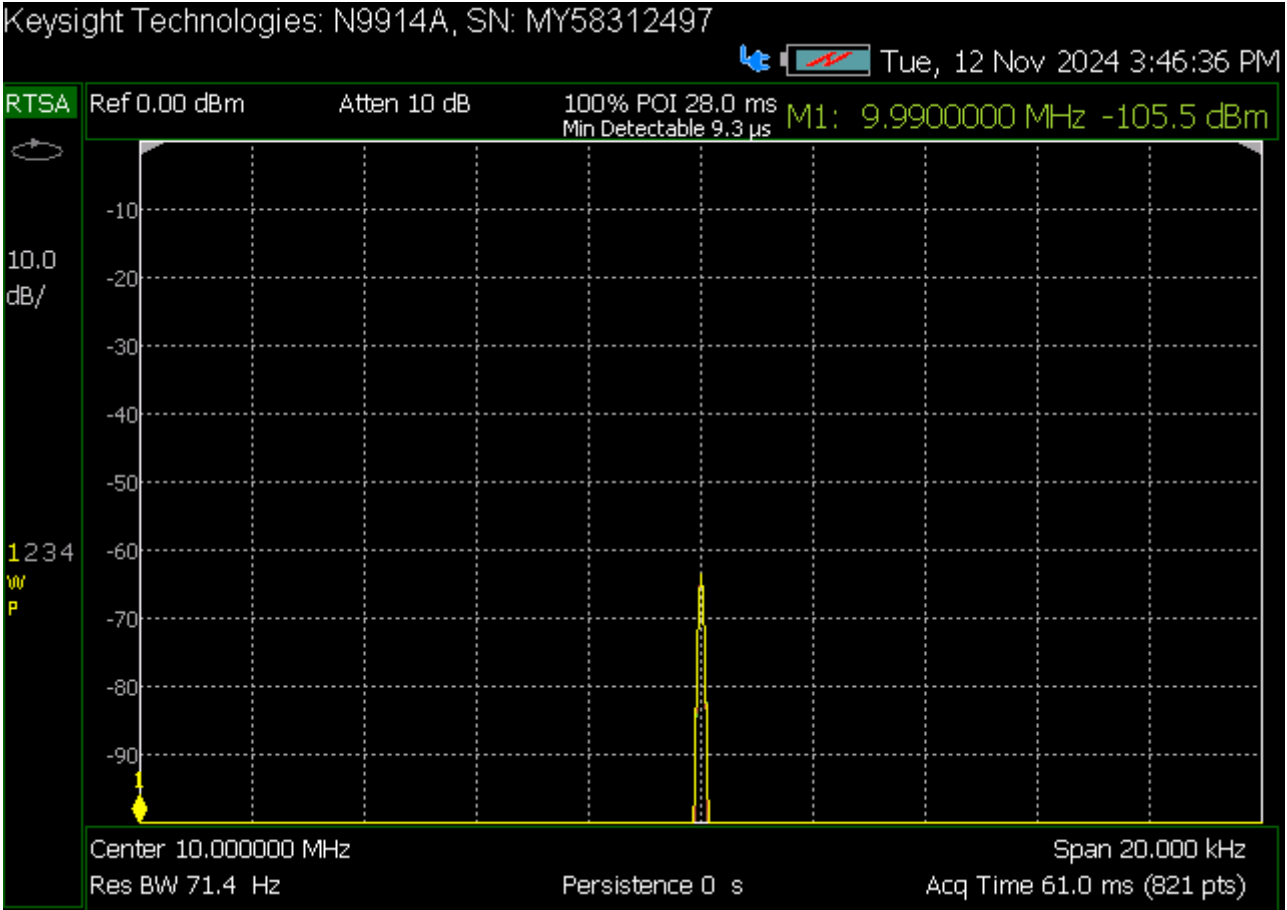




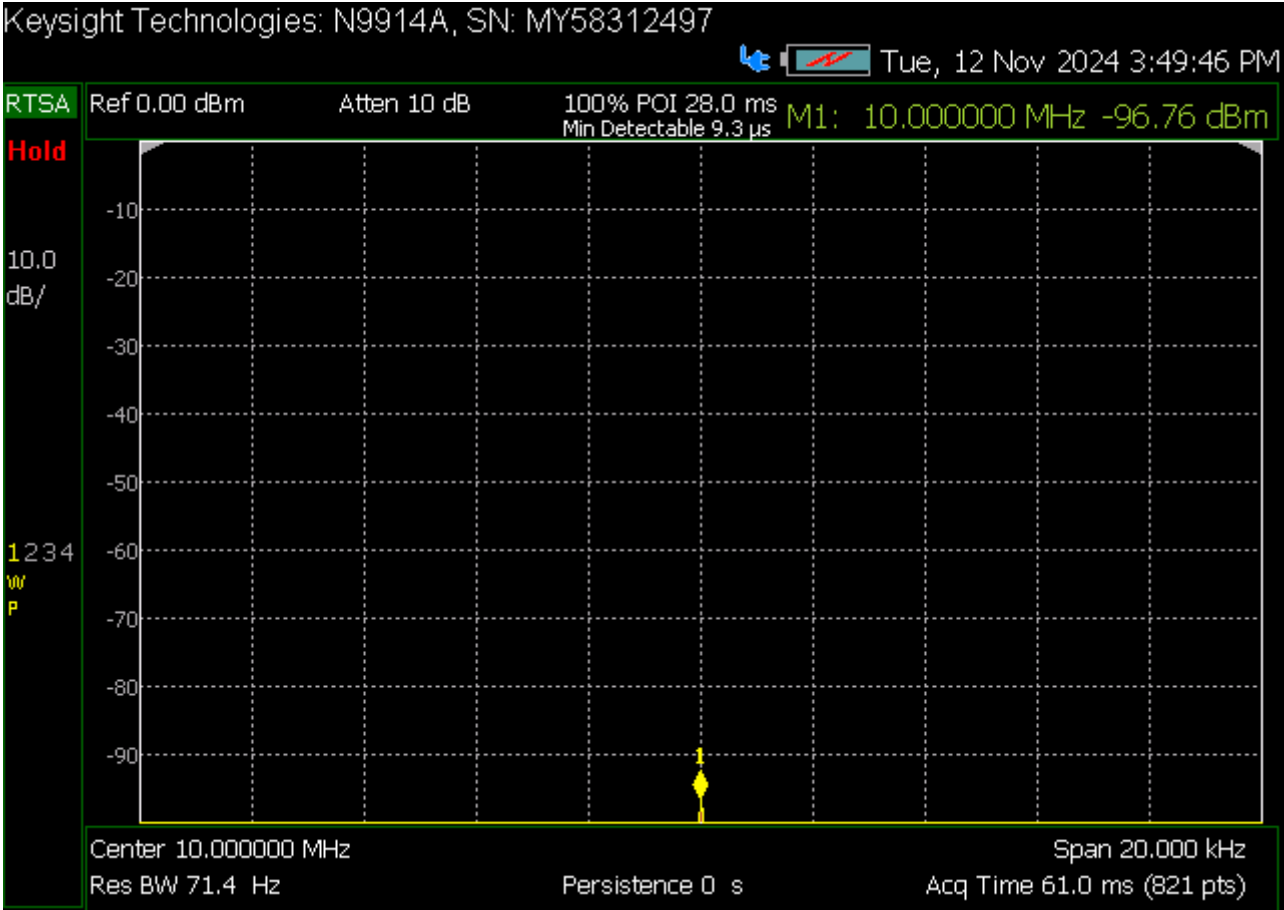
# Stripline - Radiated Emission



# Coplanar with Ground - Radiated Emission



# Coplanar with Double Ground - Radiated Emission

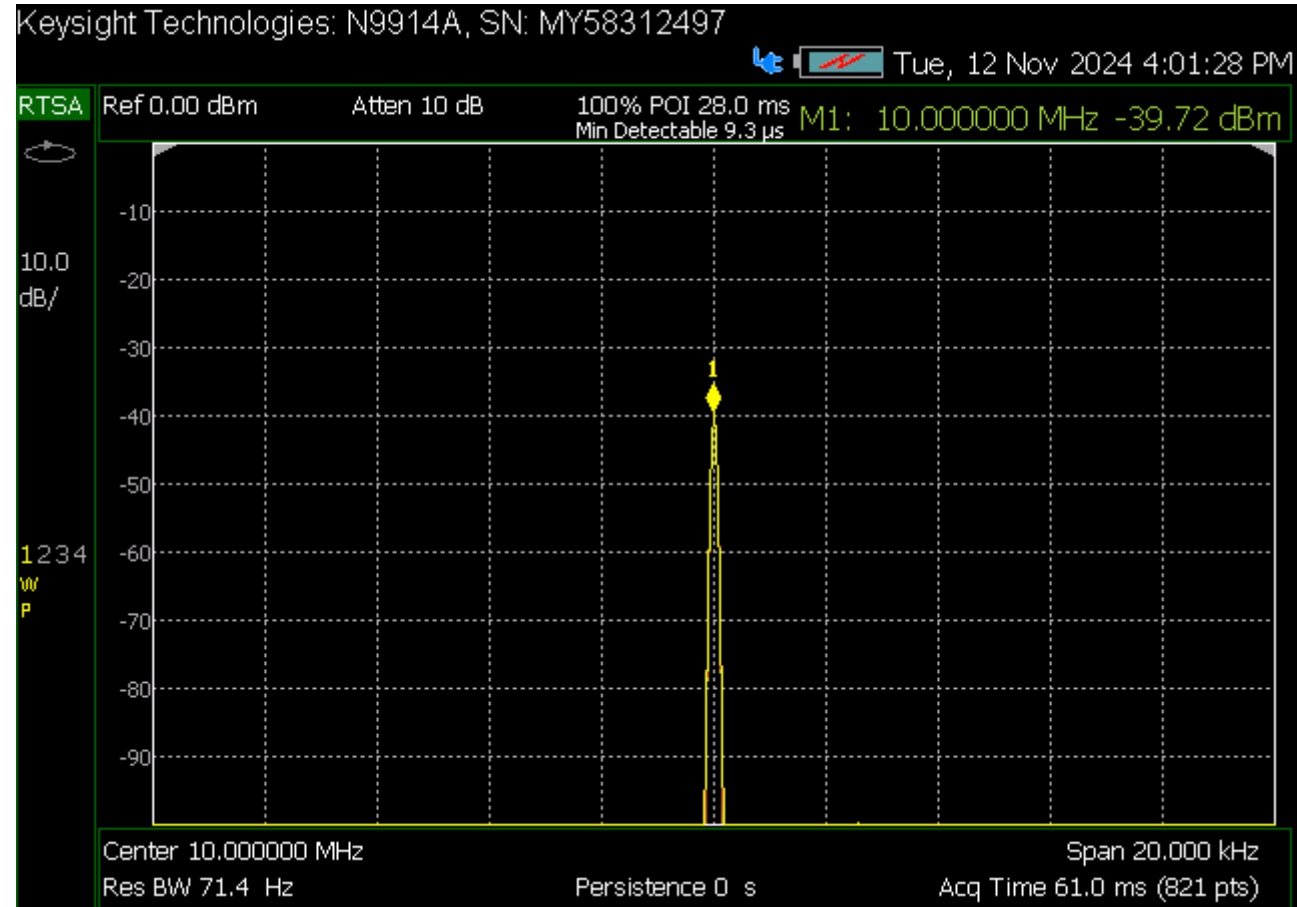


# Comparison of Transmission Lines

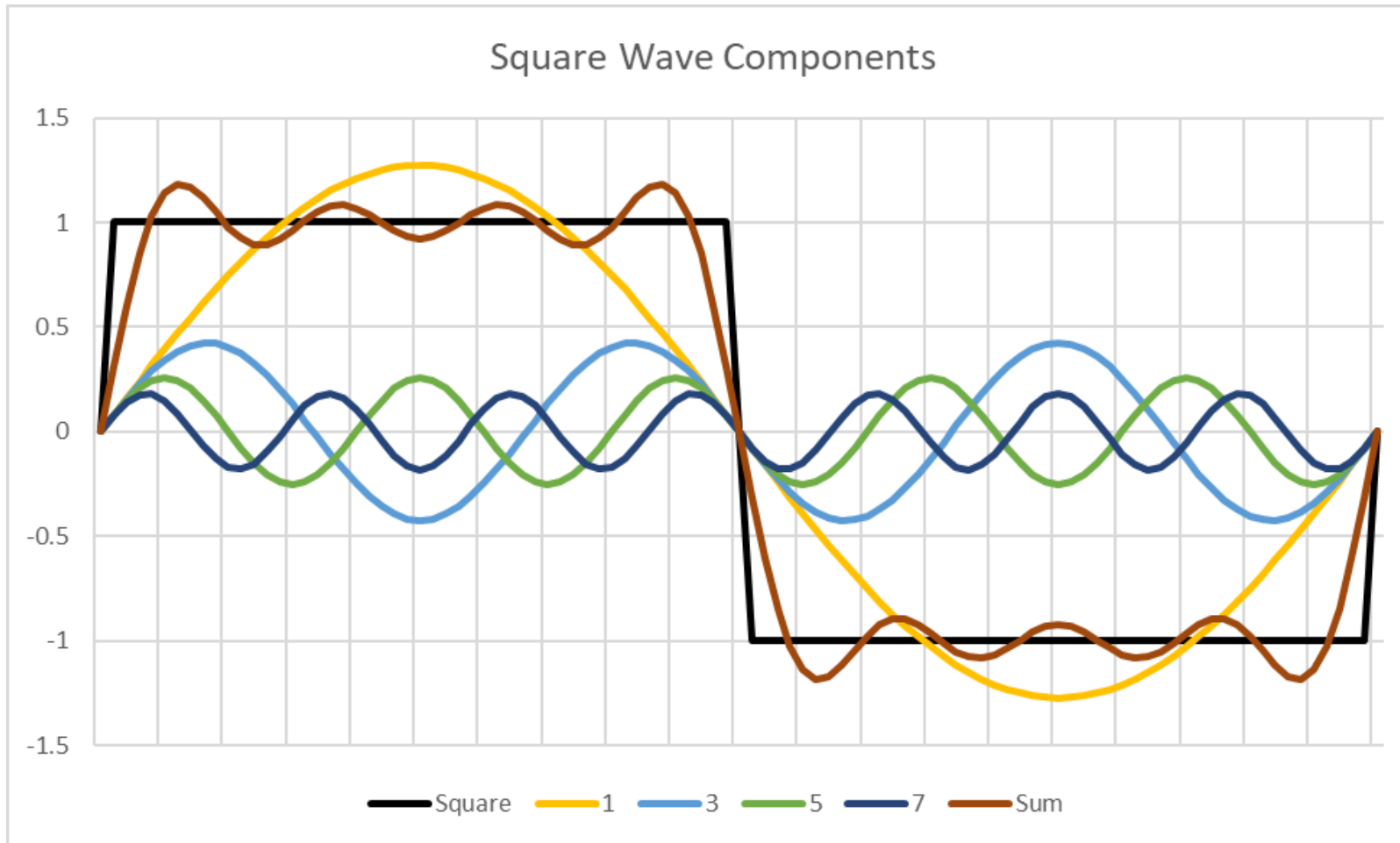
Type	Transition Frequency (kHz)	Field (dBm)
Microstrip	55.4	-56
Coplanar	64.5	-61
Stripline	39.7	-91
Coplanar with Ground	31.1	-65
Coplanar with Double Ground	34.7	-97

Ground on Outer Planes = Most Effective

# Microstrip with Broken Return - Radiated Emission



# What makes “High Frequency”? (part 2)



**A Square Wave contains Sine Waves**

# What makes “High Frequency”? (part 2)

- The **Rise Time** of a signal has an equivalent frequency:

$$f \approx 0.35 / t_r$$

- Frequency (repetition rate) tells you how often the problem happens
- Rise Time tells you how bad the problem is

Edge Rate is the important factor

# RECOMMENDATIONS



# Good Practices

- Recognize what parts of your circuit contain high frequencies
- Design for the possibility of higher frequencies than originally planned
- Design for Return Path
  - Layout critical signals first
  - The slower signals can go around, and tolerate compromises
- Don't use high-speed parts unless needed
- Don't depend on “the way we've always done it” to still work in the future

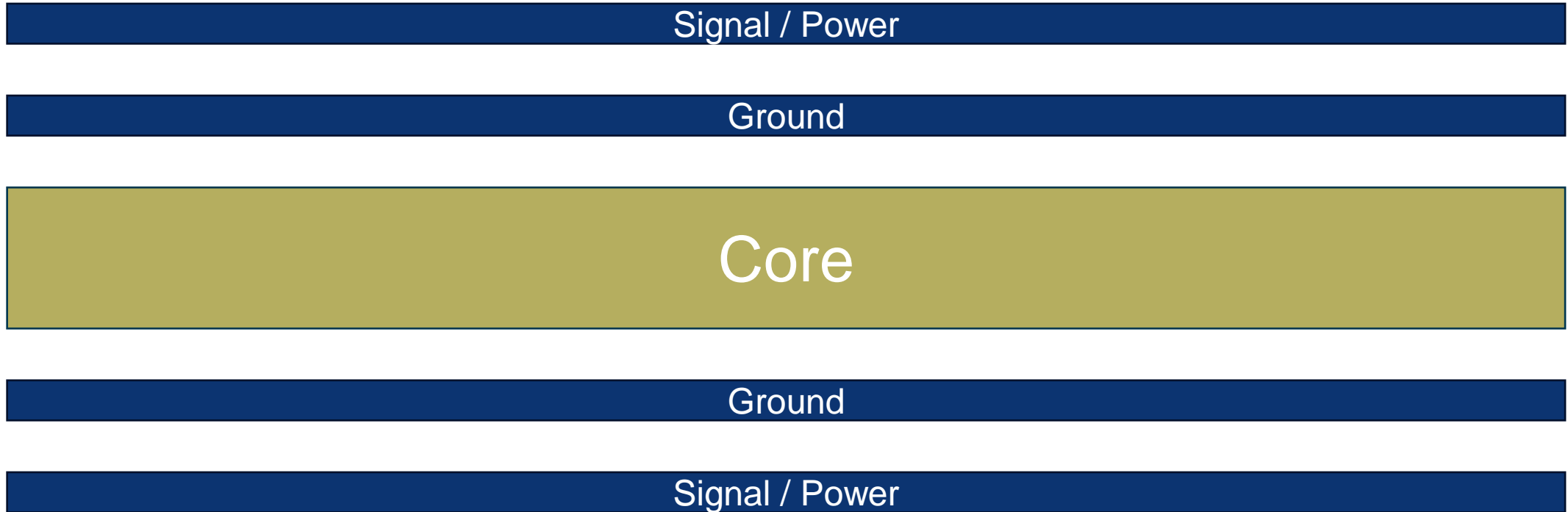
# Agency Testing

- For every circuit we make, there will be discussion about FCC testing
- The parts of a circuit that cause a failure will often be a surprise
- Attending a test can be educational (eye-opening!)

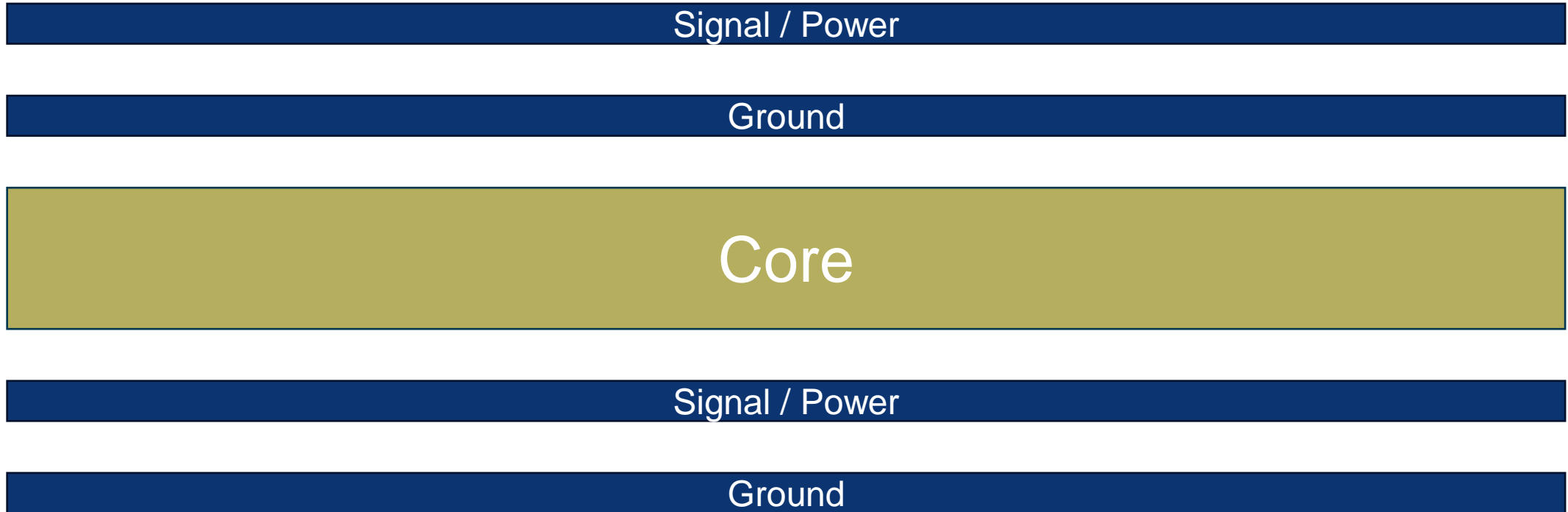
# Recommended PCB Stackup – 4 Layers

#	Name	Material	Type	Weight	Thickness	Dk
	Top Overlay		Overlay			
	Top Solder	Solder Resist	Solder Mask		0.4mil	3.5
1	Top		Signal	1oz	1.7mil	
	Dielectric 1	FR-4	Core		14mil	4.8
2	Ground		Signal	1oz	1.4mil	
	Dielectric 3		Prepreg		28mil	4.2
3	Power		Signal	1oz	1.4mil	
	Dielectric 2		Core		14mil	4.2
4	Bottom		Signal	1oz	1.4mil	
	Bottom Solder	Solder Resist	Solder Mask		0.4mil	3.5
	Bottom Overlay		Overlay			

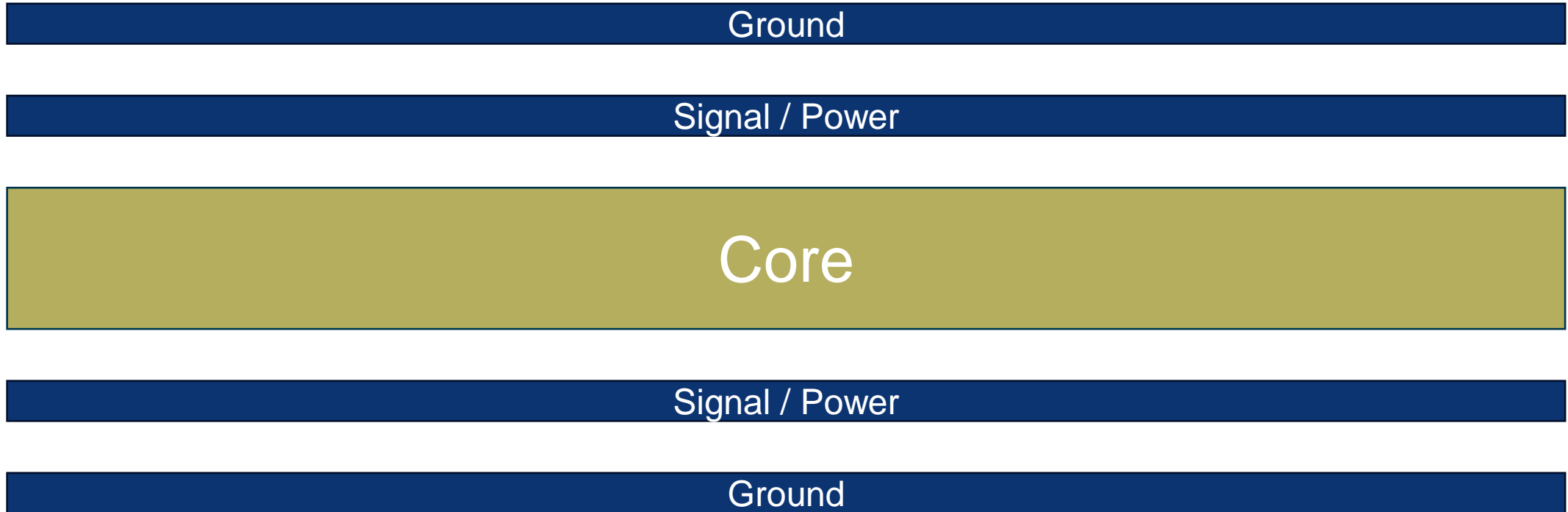
# Recommended PCB Stackup – 4 Layers



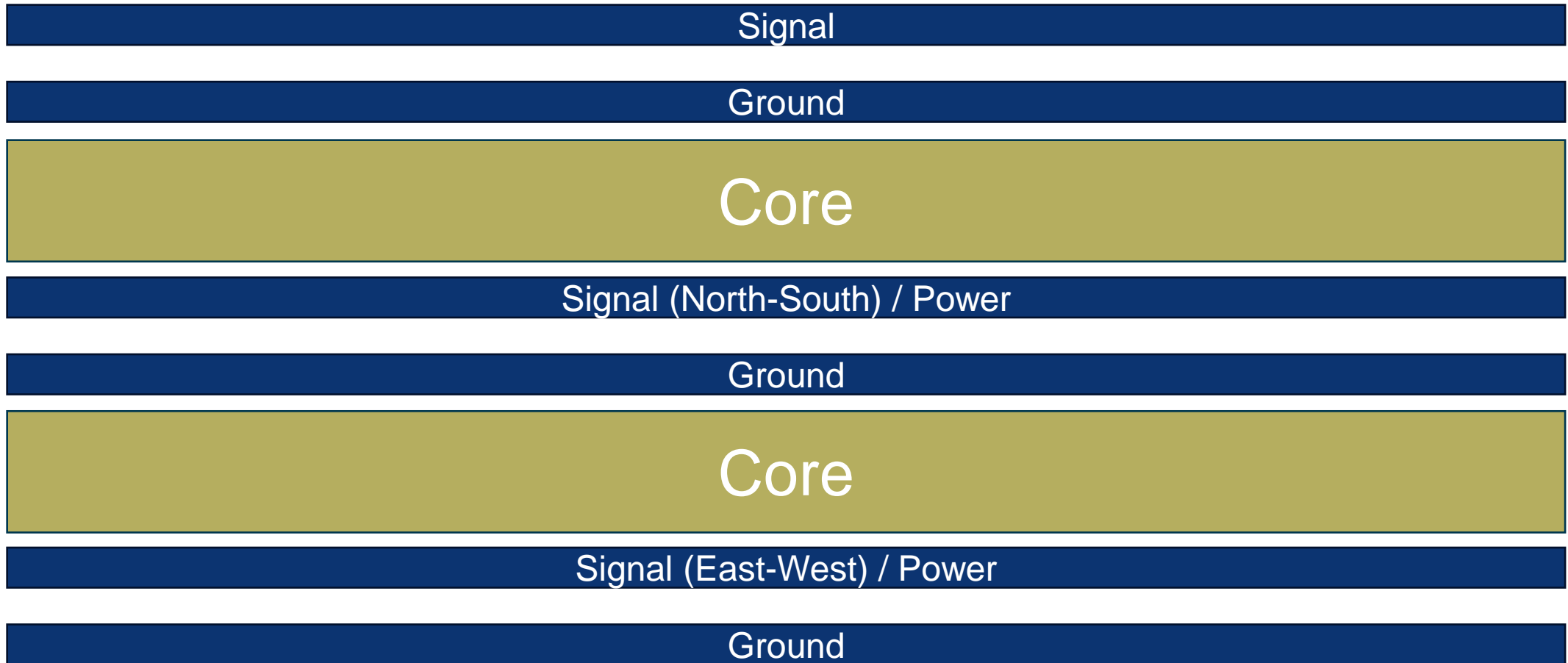
# Recommended PCB Stackup – 4 Layers



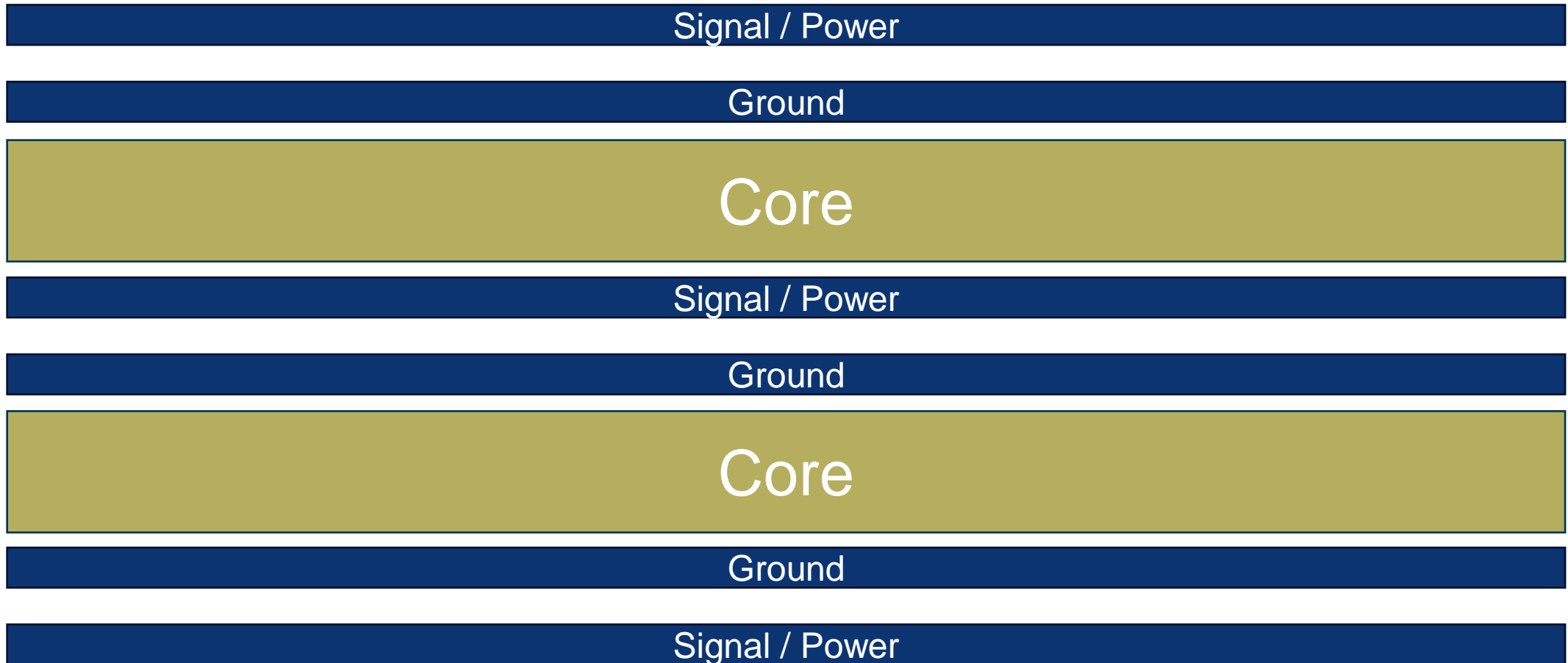
# Recommended PCB Stackup – 4 Layers



# Recommended PCB Stackup – 6 Layers

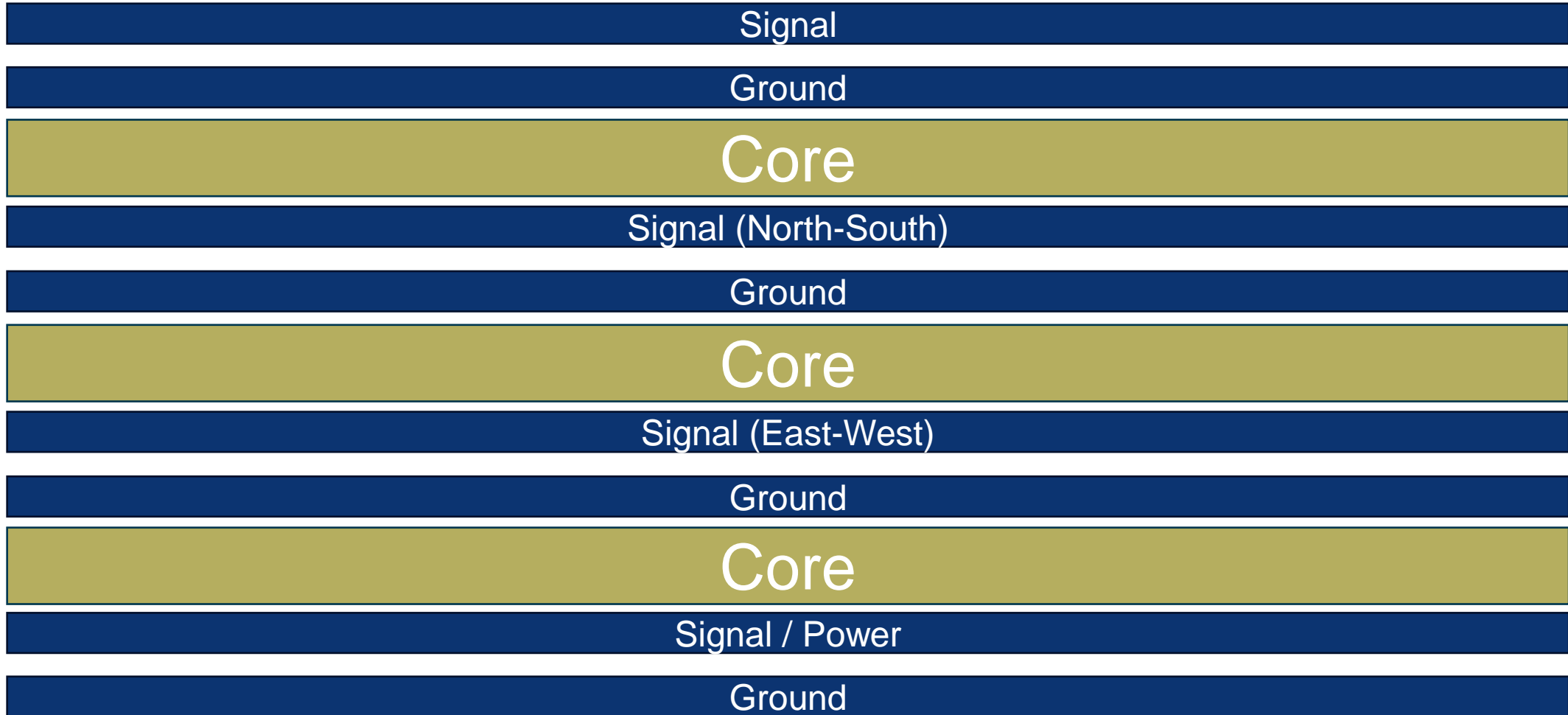


# Recommended PCB Stackup – 6 Layers

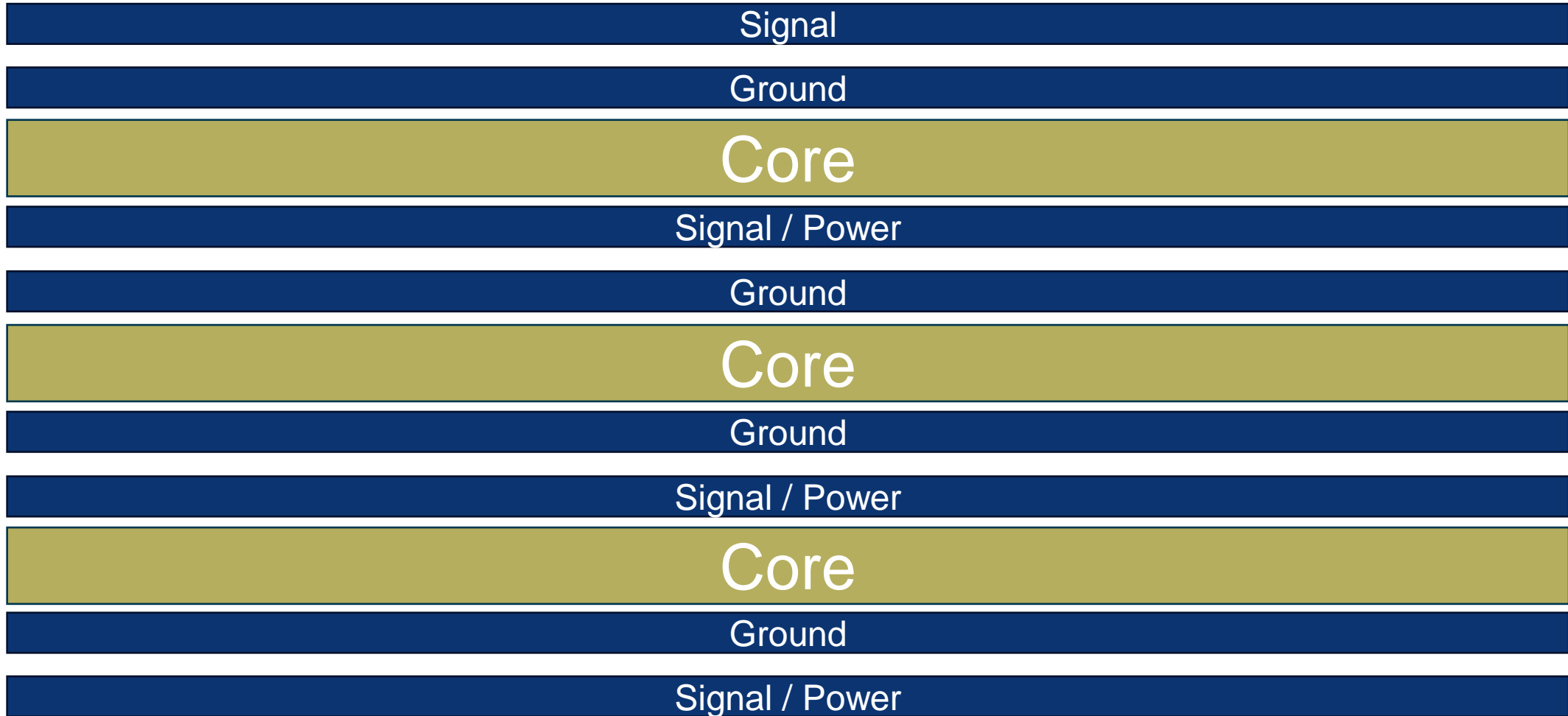




# Recommended PCB Stackup – 8 Layers

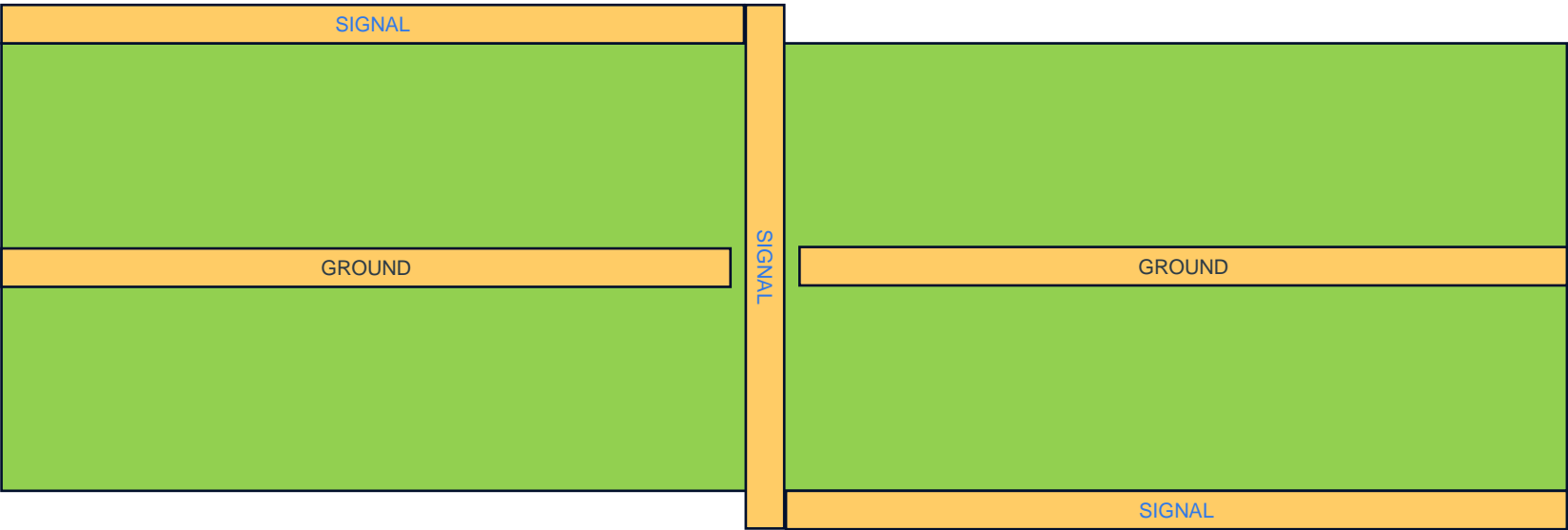


# Recommended PCB Stackup – 8 Layers



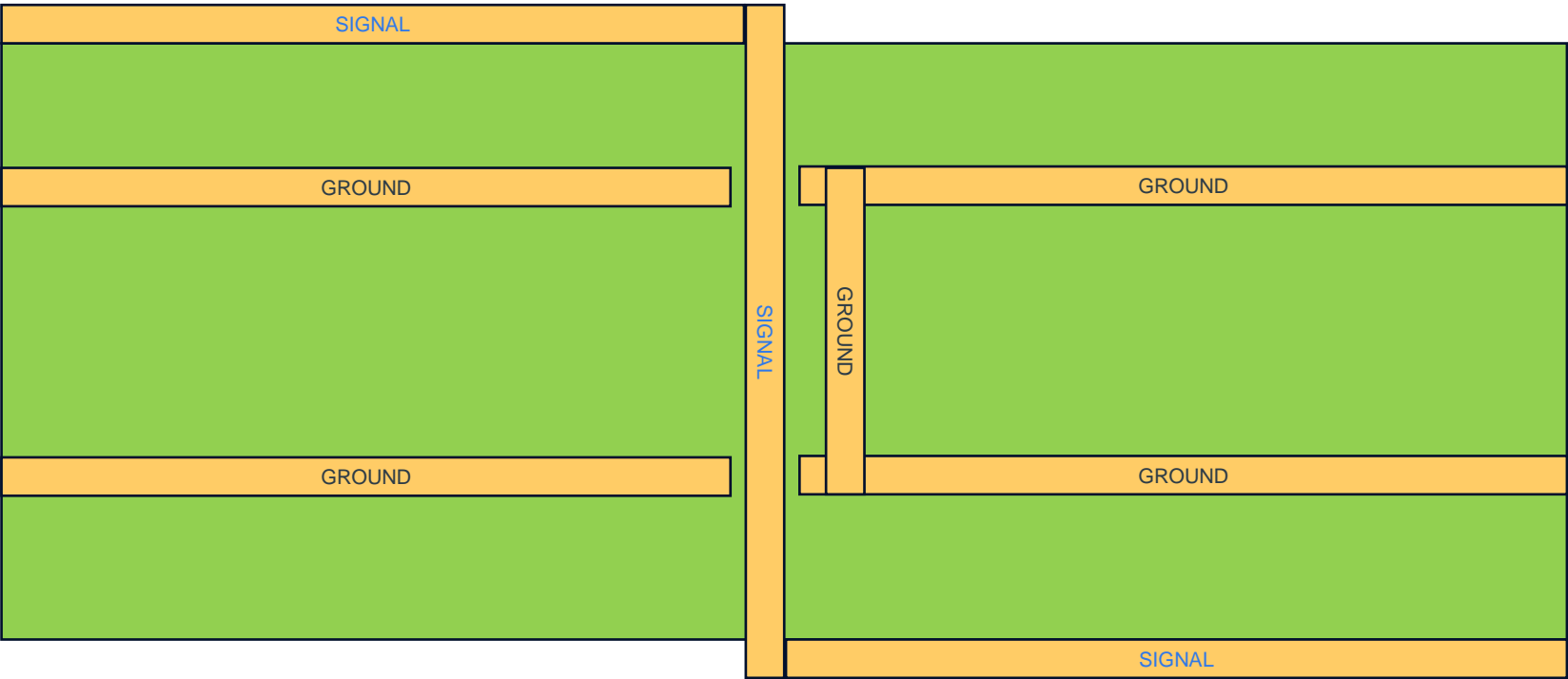
# When Signal Trace changes layers

To opposite sides of one reference layer



# When Signal Trace changes layers

To separate reference layers



# QUESTIONS AND DISCUSSION

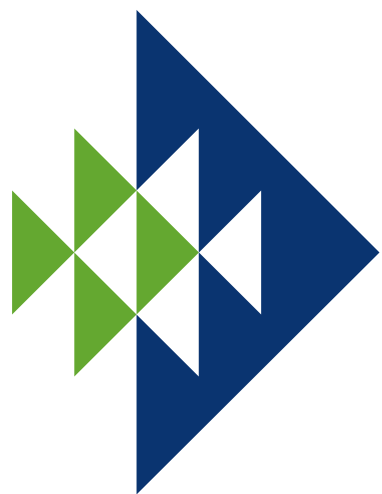
Questions?

We're Done.



Questions?

[quickmeme.com](https://www.quickmeme.com)



**PENTAIR**